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### **Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems**

**Embedded - System On Chip (SoC)** refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

### **What are Embedded - System On Chip (SoC)?**

**System On Chip (SoC)** integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions. SoCs combine a central

#### **Details**

Product Status	Discontinued at Digi-Key
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	256KB
Peripherals	DMA, POR, WDT
Connectivity	EBI/EMI, Ethernet, I <sup>2</sup> C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	1.5GHz
Primary Attributes	FPGA - 660K Logic Elements
Operating Temperature	0°C ~ 100°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-FCBGA (40x40)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/10as066k1f40e1sg">https://www.e-xfl.com/product-detail/intel/10as066k1f40e1sg</a>



## Key Advantages of Intel Arria 10 Devices

**Table 2. Key Advantages of the Intel Arria 10 Device Family**

Advantage	Supporting Feature
Enhanced core architecture	<ul style="list-style-type: none"><li>Built on TSMC's 20 nm process technology</li><li>60% higher performance than the previous generation of mid-range FPGAs</li><li>15% higher performance than the fastest previous-generation FPGA</li></ul>
High-bandwidth integrated transceivers	<ul style="list-style-type: none"><li>Short-reach rates up to 25.8 Gigabits per second (Gbps)</li><li>Backplane capability up to 12.5 Gbps</li><li>Integrated 10GBASE-KR and 40GBASE-KR4 Forward Error Correction (FEC)</li></ul>
Improved logic integration and hard IP blocks	<ul style="list-style-type: none"><li>8-input adaptive logic module (ALM)</li><li>Up to 65.6 megabits (Mb) of embedded memory</li><li>Variable-precision digital signal processing (DSP) blocks</li><li>Fractional synthesis phase-locked loops (PLLs)</li><li>Hard PCI Express Gen3 IP blocks</li><li>Hard memory controllers and PHY up to 2,400 Megabits per second (Mbps)</li></ul>
Second generation hard processor system (HPS) with integrated ARM* Cortex*-A9* MPCore* processor	<ul style="list-style-type: none"><li>Tight integration of a dual-core ARM Cortex-A9 MPCore processor, hard IP, and an FPGA in a single Intel Arria 10 system-on-a-chip (SoC)</li><li>Supports over 128 Gbps peak bandwidth with integrated data coherency between the processor and the FPGA fabric</li></ul>
Advanced power savings	<ul style="list-style-type: none"><li>Comprehensive set of advanced power saving features</li><li>Power-optimized MultiTrack routing and core architecture</li><li>Up to 40% lower power compared to previous generation of mid-range FPGAs</li><li>Up to 60% lower power compared to previous generation of high-end FPGAs</li></ul>

## Summary of Intel Arria 10 Features

**Table 3. Summary of Features for Intel Arria 10 Devices**

Feature	Description
Technology	<ul style="list-style-type: none"><li>TSMC's 20-nm SoC process technology</li><li>Allows operation at a lower <math>V_{CC}</math> level of 0.82 V instead of the 0.9 V standard <math>V_{CC}</math> core voltage</li></ul>
Packaging	<ul style="list-style-type: none"><li>1.0 mm ball-pitch FINELINE BGA packaging</li><li>0.8 mm ball-pitch Ultra FINELINE BGA packaging</li><li>Multiple devices with identical package footprints for seamless migration between different FPGA densities</li><li>Devices with compatible package footprints allow migration to next generation high-end Stratix® 10 devices</li><li>RoHS, leaded<sup>(1)</sup>, and lead-free (Pb-free) options</li></ul>
High-performance FPGA fabric	<ul style="list-style-type: none"><li>Enhanced 8-input ALM with four registers</li><li>Improved multi-track routing architecture to reduce congestion and improve compilation time</li><li>Hierarchical core clocking architecture</li><li>Fine-grained partial reconfiguration</li></ul>
Internal memory blocks	<ul style="list-style-type: none"><li>M20K—20-Kb memory blocks with hard error correction code (ECC)</li><li>Memory logic array block (MLAB)—640-bit memory</li></ul>
continued...	

(1) Contact Intel for availability.



Feature	Description
Low-power serial transceivers	<ul style="list-style-type: none"><li>Continuous operating range:<ul style="list-style-type: none"><li>Intel Arria 10 GX—1 Gbps to 17.4 Gbps</li><li>Intel Arria 10 GT—1 Gbps to 25.8 Gbps</li></ul></li><li>Backplane support:<ul style="list-style-type: none"><li>Intel Arria 10 GX—up to 12.5</li><li>Intel Arria 10 GT—up to 12.5</li></ul></li><li>Extended range down to 125 Mbps with oversampling</li><li>ATX transmit PLLs with user-configurable fractional synthesis capability</li><li>Electronic Dispersion Compensation (EDC) support for XFP, SFP+, QSFP, and CFP optical module</li><li>Adaptive linear and decision feedback equalization</li><li>Transmitter pre-emphasis and de-emphasis</li><li>Dynamic partial reconfiguration of individual transceiver channels</li></ul>
HPS (Intel Arria 10 SX devices only)	Processor and system <ul style="list-style-type: none"><li>Dual-core ARM Cortex-A9 MPCore processor—1.2 GHz CPU with 1.5 GHz overdrive capability</li><li>256 KB on-chip RAM and 64 KB on-chip ROM</li><li>System peripherals—general-purpose timers, watchdog timers, direct memory access (DMA) controller, FPGA configuration manager, and clock and reset managers</li><li>Security features—anti-tamper, secure boot, Advanced Encryption Standard (AES) and authentication (SHA)</li><li>ARM CoreSight* JTAG debug access port, trace port, and on-chip trace storage</li></ul>
	External interfaces <ul style="list-style-type: none"><li>Hard memory interface—Hard memory controller (2,400 Mbps DDR4, and 2,133 Mbps DDR3), Quad serial peripheral interface (QSPI) flash controller, NAND flash controller, direct memory access (DMA) controller, Secure Digital/MultiMediaCard (SD/MMC) controller</li><li>Communication interface— 10/100/1000 Ethernet media access control (MAC), USB On-The-Go (OTG) controllers, I<sup>2</sup>C controllers, UART 16550, serial peripheral interface (SPI), and up to 62 HPS GPIO interfaces (48 direct-share I/Os)</li></ul>
	Interconnects to core <ul style="list-style-type: none"><li>High-performance ARM AMBA* AXI bus bridges that support simultaneous read and write</li><li>HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to issue transactions to slaves in the HPS, and vice versa</li><li>Configuration bridge that allows HPS configuration manager to configure the core logic via dedicated 32-bit configuration port</li><li>FPGA-to-HPS SDRAM controller bridge—provides configuration interfaces for the multiport front end (MPFE) of the HPS SDRAM controller</li></ul>
Configuration	<ul style="list-style-type: none"><li>Tamper protection—comprehensive design protection to protect your valuable IP investments</li><li>Enhanced 256-bit advanced encryption standard (AES) design security with authentication</li><li>Configuration via protocol (CvP) using PCIe Gen1, Gen2, or Gen3</li></ul>
continued...	

(2) Intel Arria 10 devices support this external memory interface using hard PHY with soft memory controller.



Feature	Description
	<ul style="list-style-type: none"><li>Dynamic reconfiguration of the transceivers and PLLs</li><li>Fine-grained partial reconfiguration of the core fabric</li><li>Active Serial x4 Interface</li></ul>
Power management	<ul style="list-style-type: none"><li>SmartVID</li><li>Low static power device options</li><li>Programmable Power Technology</li><li>Intel Quartus Prime integrated power analysis</li></ul>
Software and tools	<ul style="list-style-type: none"><li>Intel Quartus Prime design suite</li><li>Transceiver toolkit</li><li>Platform Designer system integration tool</li><li>DSP Builder for Intel FPGAs</li><li>OpenCL™ support</li><li>Intel SoC FPGA Embedded Design Suite (EDS)</li></ul>

### Related Information

#### [Intel Arria 10 Transceiver PHY Overview](#)

Provides details on Intel Arria 10 transceivers.

## Intel Arria 10 Device Variants and Packages

**Table 4. Device Variants for the Intel Arria 10 Device Family**

Variant	Description
Intel Arria 10 GX	FPGA featuring 17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability.
Intel Arria 10 GT	FPGA featuring: <ul style="list-style-type: none"><li>17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability.</li><li>25.8 Gbps transceivers for supporting CAUI-4 and CEI-25G applications with CFP2 and CFP4 modules.</li></ul>
Intel Arria 10 SX	SoC integrating ARM-based HPS and FPGA featuring 17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability.

### Intel Arria 10 GX

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 GX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

### Related Information

#### [Intel FPGA Product Selector](#)

Provides the latest information on Intel products.



## Maximum Resources

**Table 5. Maximum Resource Counts for Intel Arria 10 GX Devices (GX 160, GX 220, GX 270, GX 320, and GX 480)**

Resource		Product Line				
		GX 160	GX 220	GX 270	GX 320	GX 480
Logic Elements (LE) (K)		160	220	270	320	480
ALM		61,510	80,330	101,620	119,900	183,590
Register		246,040	321,320	406,480	479,600	734,360
Memory (Kb)	M20K	8,800	11,740	15,000	17,820	28,620
	MLAB	1,050	1,690	2,452	2,727	4,164
Variable-precision DSP Block		156	192	830	985	1,368
18 x 19 Multiplier		312	384	1,660	1,970	2,736
PLL	Fractional Synthesis	6	6	8	8	12
	I/O	6	6	8	8	12
17.4 Gbps Transceiver		12	12	24	24	36
GPIO <sup>(3)</sup>		288	288	384	384	492
LVDS Pair <sup>(4)</sup>		120	120	168	168	222
PCIe Hard IP Block		1	1	2	2	2
Hard Memory Controller		6	6	8	8	12

<sup>(3)</sup> The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

<sup>(4)</sup> Each LVDS I/O pair can be used as differential input or output.



## Maximum Resources

**Table 10. Maximum Resource Counts for Intel Arria 10 GT Devices**

Resource		Product Line	
		GT 900	GT 1150
Logic Elements (LE) (K)		900	1,150
ALM		339,620	427,200
Register		1,358,480	1,708,800
Memory (Kb)	M20K	48,460	54,260
	MLAB	9,386	12,984
Variable-precision DSP Block		1,518	1,518
18 x 19 Multiplier		3,036	3,036
PLL	Fractional Synthesis	32	32
	I/O	16	16
Transceiver	17.4 Gbps	72 <sup>(5)</sup>	72 <sup>(5)</sup>
	25.8 Gbps	6	6
GPIO <sup>(6)</sup>		624	624
LVDS Pair <sup>(7)</sup>		312	312
PCIe Hard IP Block		4	4
Hard Memory Controller		16	16

### Related Information

#### Intel Arria 10 GT Channel Usage

Configuring GT/GX channels in Intel Arria 10 GT devices.

## Package Plan

**Table 11. Package Plan for Intel Arria 10 GT Devices**

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	SF45 (45 mm x 45 mm, 1932-pin FBGA)		
	3 V I/O	LVDS I/O	XCVR
GT 900	—	624	72
GT 1150	—	624	72

<sup>(5)</sup> If all 6 GT channels are in use, 12 of the GX channels are not usable.

<sup>(6)</sup> The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

<sup>(7)</sup> Each LVDS I/O pair can be used as differential input or output.



### Related Information

I/O and High-Speed Differential I/O Interfaces in Intel Arria 10 Devices chapter, Intel Arria 10 Device Handbook

Provides the number of 3 V and LVDS I/Os, and LVDS channels for each Intel Arria 10 device package.

## Intel Arria 10 SX

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 SX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

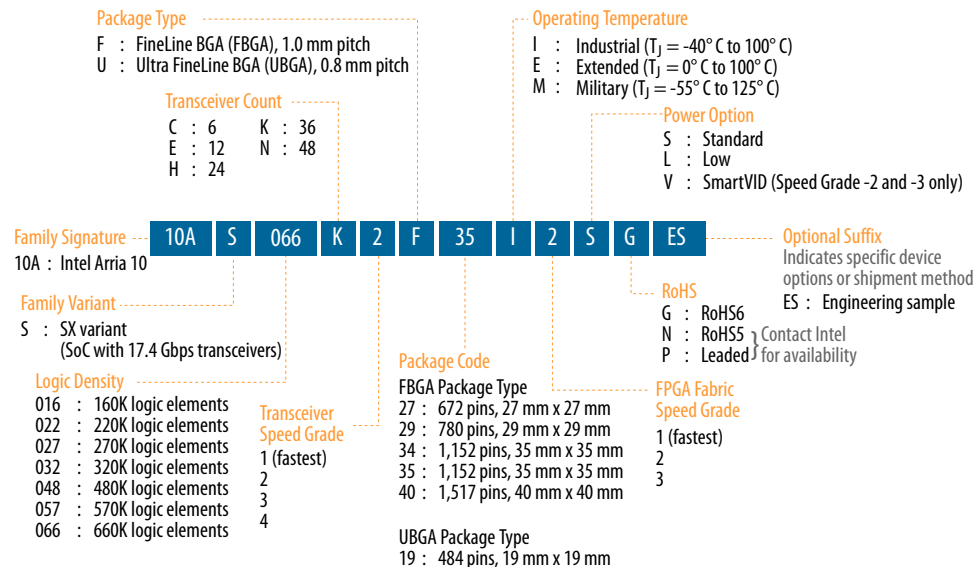
### Related Information

Intel FPGA Product Selector

Provides the latest information on Intel products.

## Available Options

**Figure 3. Sample Ordering Code and Available Options for Intel Arria 10 SX Devices**



### Related Information

Transceiver Performance for Intel Arria 10 GX/SX Devices

Provides more information about the transceiver speed grade.



## Maximum Resources

**Table 12. Maximum Resource Counts for Intel Arria 10 SX Devices**

Resource		Product Line						
		SX 160	SX 220	SX 270	SX 320	SX 480	SX 570	SX 660
Logic Elements (LE) (K)		160	220	270	320	480	570	660
ALM		61,510	80,330	101,620	119,900	183,590	217,080	251,680
Register		246,040	321,320	406,480	479,600	734,360	868,320	1,006,720
Memory (Kb)	M20K	8,800	11,740	15,000	17,820	28,620	36,000	42,620
	MLAB	1,050	1,690	2,452	2,727	4,164	5,096	5,788
Variable-precision DSP Block		156	192	830	985	1,368	1,523	1,687
18 x 19 Multiplier		312	384	1,660	1,970	2,736	3,046	3,374
PLL	Fractional Synthesis	6	6	8	8	12	16	16
	I/O	6	6	8	8	12	16	16
17.4 Gbps Transceiver		12	12	24	24	36	48	48
GPIO <sup>(8)</sup>		288	288	384	384	492	696	696
LVDS Pair <sup>(9)</sup>		120	120	168	168	174	324	324
PCIe Hard IP Block		1	1	2	2	2	2	2
Hard Memory Controller		6	6	8	8	12	16	16
ARM Cortex-A9 MPCore Processor		Yes	Yes	Yes	Yes	Yes	Yes	Yes

## Package Plan

**Table 13. Package Plan for Intel Arria 10 SX Devices (U19, F27, F29, and F34)**

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	U19 (19 mm × 19 mm, 484-pin UBGGA)			F27 (27 mm × 27 mm, 672-pin FBGA)			F29 (29 mm × 29 mm, 780-pin FBGA)			F34 (35 mm × 35 mm, 1152-pin FBGA)		
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
SX 160	48	144	6	48	192	12	48	240	12	—	—	—
SX 220	48	144	6	48	192	12	48	240	12	—	—	—
SX 270	—	—	—	48	192	12	48	312	12	48	336	24
SX 320	—	—	—	48	192	12	48	312	12	48	336	24
continued...												

<sup>(8)</sup> The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

<sup>(9)</sup> Each LVDS I/O pair can be used as differential input or output.





Product Line	U19 (19 mm × 19 mm, 484-pin UBGA)			F27 (27 mm × 27 mm, 672-pin FBGA)			F29 (29 mm × 29 mm, 780-pin FBGA)			F34 (35 mm × 35 mm, 1152-pin FBGA)		
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
SX 480	—	—	—	—	—	—	48	312	12	48	444	24
SX 570	—	—	—	—	—	—	—	—	—	48	444	24
SX 660	—	—	—	—	—	—	—	—	—	48	444	24

**Table 14. Package Plan for Intel Arria 10 SX Devices (F35, KF40, and NF40)**

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	F35 (35 mm × 35 mm, 1152-pin FBGA)			KF40 (40 mm × 40 mm, 1517-pin FBGA)			NF40 (40 mm × 40 mm, 1517-pin FBGA)		
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
SX 270	48	336	24	—	—	—	—	—	—
SX 320	48	336	24	—	—	—	—	—	—
SX 480	48	348	36	—	—	—	—	—	—
SX 570	48	348	36	96	600	36	48	540	48
SX 660	48	348	36	96	600	36	48	540	48

#### Related Information

[I/O and High-Speed Differential I/O Interfaces in Intel Arria 10 Devices chapter, Intel Arria 10 Device Handbook](#)

Provides the number of 3 V and LVDS I/Os, and LVDS channels for each Intel Arria 10 device package.



## I/O Vertical Migration for Intel Arria 10 Devices

**Figure 4. Migration Capability Across Intel Arria 10 Product Lines**

- The arrows indicate the migration paths. The devices included in each vertical migration path are shaded. Devices with fewer resources in the same path have lighter shades.
- To achieve the full I/O migration across product lines in the same migration path, restrict I/Os and transceivers usage to match the product line with the lowest I/O and transceiver counts.
- An LVDS I/O bank in the source device may be mapped to a 3 V I/O bank in the target device. To use memory interface clock frequency higher than 533 MHz, assign external memory interface pins only to banks that are LVDS I/O in both devices.
- There may be nominal 0.15 mm package height difference between some product lines in the same package type.
- Some migration paths are not shown in the Intel Quartus Prime software **Pin Migration View**.

Variant	Product Line	Package										
		U19	F27	F29	F34	F35	KF40	NF40	RF40	NF45	SF45	UF45
Intel® Arria® 10 GX	GX 160	↑	↑	↑								
	GX 220	↓	↑	↑								
	GX 270		↑	↑	↑	↑						
	GX 320		↓	↑	↑	↑						
	GX 480			↓	↑	↑						
	GX 570				↑	↑	↑	↑				
	GX 660				↑	↓	↑	↑	↑	↑	↑	↑
	GX 900				↑			↑	↑	↑	↑	↑
	GX 1150				↑			↑	↑	↑	↑	↑
	GT 900										↑	↑
	GT 1150										↓	↑
Intel Arria 10 SX	SX 160	↑	↑	↑								
	SX 220	↓	↑	↑								
	SX 270		↑	↑	↑	↑						
	SX 320		↓	↑	↑	↑						
	SX 480			↓	↑	↑						
	SX 570				↑	↑	↑	↑				
	SX 660				↑	↓	↑	↑				

**Note:** To verify the pin migration compatibility, use the **Pin Migration View** window in the Intel Quartus Prime software Pin Planner.

## Adaptive Logic Module

Intel Arria 10 devices use a 20 nm ALM as the basic building block of the logic fabric.

The ALM architecture is the same as the previous generation FPGAs, allowing for efficient implementation of logic functions and easy conversion of IP between the device generations.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than the traditional two-register per LUT architecture.



Features for floating-point arithmetic:

- A completely hardened architecture that supports multiplication, addition, subtraction, multiply-add, and multiply-subtract
- Multiplication with accumulation capability and a dynamic accumulator reset control
- Multiplication with cascade summation capability
- Multiplication with cascade subtraction capability
- Complex multiplication
- Direct vector dot product
- Systolic FIR filter

**Table 15. Variable-Precision DSP Block Configurations for Intel Arria 10 Devices**

Usage Example	Multiplier Size (Bit)	DSP Block Resources
Medium precision fixed point	Two 18 x 19	1
High precision fixed or Single precision floating point	One 27 x 27	1
Fixed point FFTs	One 19 x 36 with external adder	1
Very high precision fixed point	One 36 x 36 with external adder	2
Double precision floating point	One 54 x 54 with external adder	4

**Table 16. Resources for Fixed-Point Arithmetic in Intel Arria 10 Devices**

The table lists the variable-precision DSP resources by bit precision for each Intel Arria 10 device.

Variant	Product Line	Variable-precision DSP Block	Independent Input and Output Multiplications Operator		18 x 19 Multiplier Adder Sum Mode	18 x 18 Multiplier Adder Summed with 36 bit Input
			18 x 19 Multiplier	27 x 27 Multiplier		
Intel Arria 10 GX	GX 160	156	312	156	156	156
	GX 220	192	384	192	192	192
	GX 270	830	1,660	830	830	830
	GX 320	984	1,968	984	984	984
	GX 480	1,368	2,736	1,368	1,368	1,368
	GX 570	1,523	3,046	1,523	1,523	1,523
	GX 660	1,687	3,374	1,687	1,687	1,687
	GX 900	1,518	3,036	1,518	1,518	1,518
	GX 1150	1,518	3,036	1,518	1,518	1,518
Intel Arria 10 GT	GT 900	1,518	3,036	1,518	1,518	1,518
	GT 1150	1,518	3,036	1,518	1,518	1,518
Intel Arria 10 SX	SX 160	156	312	156	156	156
	SX 220	192	384	192	192	192
	SX 270	830	1,660	830	830	830

*continued...*



Variant	Product Line	Variable-precision DSP Block	Independent Input and Output Multiplications Operator		18 x 19 Multiplier Adder Sum Mode	18 x 18 Multiplier Adder Summed with 36 bit Input
			18 x 19 Multiplier	27 x 27 Multiplier		
	SX 320	984	1,968	984	984	984
	SX 480	1,368	2,736	1,368	1,368	1,368
	SX 570	1,523	3,046	1,523	1,523	1,523
	SX 660	1,687	3,374	1,687	1,687	1,687

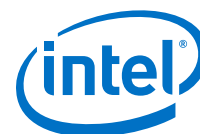
**Table 17. Resources for Floating-Point Arithmetic in Intel Arria 10 Devices**

The table lists the variable-precision DSP resources by bit precision for each Intel Arria 10 device.

Variant	Product Line	Variable-precision DSP Block	Single Precision Floating-Point Multiplication Mode	Single-Precision Floating-Point Adder Mode	Single-Precision Floating-Point Multiply Accumulate Mode	Peak Giga Floating-Point Operations per Second (GFLOPs)
Intel Arria 10 GX	GX 160	156	156	156	156	140
	GX 220	192	192	192	192	173
	GX 270	830	830	830	830	747
	GX 320	984	984	984	984	886
	GX 480	1,369	1,368	1,368	1,368	1,231
	GX 570	1,523	1,523	1,523	1,523	1,371
	GX 660	1,687	1,687	1,687	1,687	1,518
	GX 900	1,518	1,518	1,518	1,518	1,366
	GX 1150	1,518	1,518	1,518	1,518	1,366
Intel Arria 10 GT	GT 900	1,518	1,518	1,518	1,518	1,366
	GT 1150	1,518	1,518	1,518	1,518	1,366
Intel Arria 10 SX	SX 160	156	156	156	156	140
	SX 220	192	192	192	192	173
	SX 270	830	830	830	830	747
	SX 320	984	984	984	984	886
	SX 480	1,369	1,368	1,368	1,368	1,231
	SX 570	1,523	1,523	1,523	1,523	1,371
	SX 660	1,687	1,687	1,687	1,687	1,518

## Embedded Memory Blocks

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.



## Types of Embedded Memory

The Intel Arria 10 devices contain two types of memory blocks:

- 20 Kb M20K blocks—blocks of dedicated memory resources. The M20K blocks are ideal for larger memory arrays while still providing a large number of independent ports.
- 640 bit memory logic array blocks (MLABs)—enhanced memory blocks that are configured from dual-purpose logic array blocks (LABs). The MLABs are ideal for wide and shallow memory arrays. The MLABs are optimized for implementation of shift registers for digital signal processing (DSP) applications, wide and shallow FIFO buffers, and filter delay lines. Each MLAB is made up of ten adaptive logic modules (ALMs). In the Intel Arria 10 devices, you can configure these ALMs as ten 32 x 2 blocks, giving you one 32 x 20 simple dual-port SRAM block per MLAB.

## Embedded Memory Capacity in Intel Arria 10 Devices

**Table 18. Embedded Memory Capacity and Distribution in Intel Arria 10 Devices**

Variant	Product Line	M20K		MLAB		Total RAM Bit (Kb)
		Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	
Intel Arria 10 GX	GX 160	440	8,800	1,680	1,050	9,850
	GX 220	587	11,740	2,703	1,690	13,430
	GX 270	750	15,000	3,922	2,452	17,452
	GX 320	891	17,820	4,363	2,727	20,547
	GX 480	1,431	28,620	6,662	4,164	32,784
	GX 570	1,800	36,000	8,153	5,096	41,096
	GX 660	2,131	42,620	9,260	5,788	48,408
	GX 900	2,423	48,460	15,017	9,386	57,846
	GX 1150	2,713	54,260	20,774	12,984	67,244
Intel Arria 10 GT	GT 900	2,423	48,460	15,017	9,386	57,846
	GT 1150	2,713	54,260	20,774	12,984	67,244
Intel Arria 10 SX	SX 160	440	8,800	1,680	1,050	9,850
	SX 220	587	11,740	2,703	1,690	13,430
	SX 270	750	15,000	3,922	2,452	17,452
	SX 320	891	17,820	4,363	2,727	20,547
	SX 480	1,431	28,620	6,662	4,164	32,784
	SX 570	1,800	36,000	8,153	5,096	41,096
	SX 660	2,131	42,620	9,260	5,788	48,408

## Embedded Memory Configurations for Single-port Mode

**Table 19. Single-port Embedded Memory Configurations for Intel Arria 10 Devices**

This table lists the maximum configurations supported for single-port RAM and ROM modes.

Memory Block	Depth (bits)	Programmable Width
MLAB	32	x16, x18, or x20
	64 <sup>(10)</sup>	x8, x9, x10
M20K	512	x40, x32
	1K	x20, x16
	2K	x10, x8
	4K	x5, x4
	8K	x2
	16K	x1

## Clock Networks and PLL Clock Sources

The clock network architecture is based on Intel's global, regional, and peripheral clock structure. This clock structure is supported by dedicated clock input pins, fractional clock synthesis PLLs, and integer I/O PLLs.

### Clock Networks

The Intel Arria 10 core clock networks are capable of up to 800 MHz fabric operation across the full industrial temperature range. For the external memory interface, the clock network supports the hard memory controller with speeds up to 2,400 Mbps in a quarter-rate transfer.

To reduce power consumption, the Intel Quartus Prime software identifies all unused sections of the clock network and powers them down.

### Fractional Synthesis and I/O PLLs

Intel Arria 10 devices contain up to 32 fractional synthesis PLLs and up to 16 I/O PLLs that are available for both specific and general purpose uses in the core:

- Fractional synthesis PLLs—located in the column adjacent to the transceiver blocks
- I/O PLLs—located in each bank of the 48 I/Os

### Fractional Synthesis PLLs

You can use the fractional synthesis PLLs to:

- Reduce the number of oscillators that are required on your board
- Reduce the number of clock pins that are used in the device by synthesizing multiple clock frequencies from a single reference clock source

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<sup>(10)</sup> Supported through software emulation and consumes additional MLAB blocks.



The fractional synthesis PLLs support the following features:

- Reference clock frequency synthesis for transceiver CMU and Advanced Transmit (ATX) PLLs
- Clock network delay compensation
- Zero-delay buffering
- Direct transmit clocking for transceivers
- Independently configurable into two modes:
  - Conventional integer mode equivalent to the general purpose PLL
  - Enhanced fractional mode with third order delta-sigma modulation
- PLL cascading

## I/O PLLs

The integer mode I/O PLLs are located in each bank of 48 I/Os. You can use the I/O PLLs to simplify the design of external memory and high-speed LVDS interfaces.

In each I/O bank, the I/O PLLs are adjacent to the hard memory controllers and LVDS SERDES. Because these PLLs are tightly coupled with the I/Os that need to use them, it makes it easier to close timing.

You can use the I/O PLLs for general purpose applications in the core such as clock network delay compensation and zero-delay buffering.

Intel Arria 10 devices support PLL-to-PLL cascading.

## FPGA General Purpose I/O

Intel Arria 10 devices offer highly configurable GPIOs. Each I/O bank contains 48 general purpose I/Os and a high-efficiency hard memory controller.

The following list describes the features of the GPIOs:

- Consist of 3 V I/Os for high-voltage application and LVDS I/Os for differential signaling
  - Up to two 3 V I/O banks, available in some devices, that support up to 3 V I/O standards
  - LVDS I/O banks that support up to 1.8 V I/O standards
- Support a wide range of single-ended and differential I/O interfaces
- LVDS speeds up to 1.6 Gbps
- Each LVDS pair of pins has differential input and output buffers, allowing you to configure the LVDS direction for each pair.
- Programmable bus hold and weak pull-up
- Programmable differential output voltage ( $V_{OD}$ ) and programmable pre-emphasis

**Table 20. Memory Standards Supported by the Hard Memory Controller**

This table lists the overall capability of the hard memory controller. For specific details, refer to the External Memory Interface Spec Estimator and Intel Arria 10 Device Datasheet.

Memory Standard	Rate Support	Ping Pong PHY Support	Maximum Frequency (MHz)
DDR4 SDRAM	Quarter rate	Yes	1,067
		—	1,200
DDR3 SDRAM	Half rate	Yes	533
		—	667
	Quarter rate	Yes	1,067
		—	1,067
DDR3L SDRAM	Half rate	Yes	533
		—	667
	Quarter rate	Yes	933
		—	933
LPDDR3 SDRAM	Half rate	—	533
	Quarter rate	—	800

**Table 21. Memory Standards Supported by the Soft Memory Controller**

Memory Standard	Rate Support	Maximum Frequency (MHz)
RLDRAM 3 <sup>(11)</sup>	Quarter rate	1,200
QDR IV SRAM <sup>(11)</sup>	Quarter rate	1,067
QDR II SRAM	Full rate	333
	Half rate	633
QDR II+ SRAM	Full rate	333
	Half rate	633
QDR II+ Xtreme SRAM	Full rate	333
	Half rate	633

**Table 22. Memory Standards Supported by the HPS Hard Memory Controller**

The hard processor system (HPS) is available in Intel Arria 10 SoC devices only.

Memory Standard	Rate Support	Maximum Frequency (MHz)
DDR4 SDRAM	Half rate	1,200
DDR3 SDRAM	Half rate	1,067
DDR3L SDRAM	Half rate	933

<sup>(11)</sup> Intel Arria 10 devices support this external memory interface using hard PHY with soft memory controller.





The scalable hard IP supports multiple independent 10GbE ports while using a single PLL for all the 10GBASE-R PCS instantiations, which saves on core logic resources and clock networks:

- Simplifies multiport 10GbE systems compared to XAUI interfaces that require an external XAUI-to-10G PHY.
- Incorporates Electronic Dispersion Compensation (EDC), which enables direct connection to standard 10 Gbps XFP and SFP+ pluggable optical modules.
- Supports backplane Ethernet applications and includes a hard 10GBASE-KR Forward Error Correction (FEC) circuit that you can use for 10 Gbps and 40 Gbps applications.

The 10 Gbps Ethernet PCS hard IP and 10GBASE-KR FEC are present in every transceiver channel.

#### Related Information

[PCS Features](#) on page 30

## Low Power Serial Transceivers

Intel Arria 10 FPGAs and SoCs include lowest power transceivers that deliver high bandwidth, throughput and low latency.

Intel Arria 10 devices deliver the industry's lowest power consumption per transceiver channel:

- 12.5 Gbps transceivers at as low as 242 mW
- 10 Gbps transceivers at as low as 168 mW
- 6 Gbps transceivers at as low as 117 mW

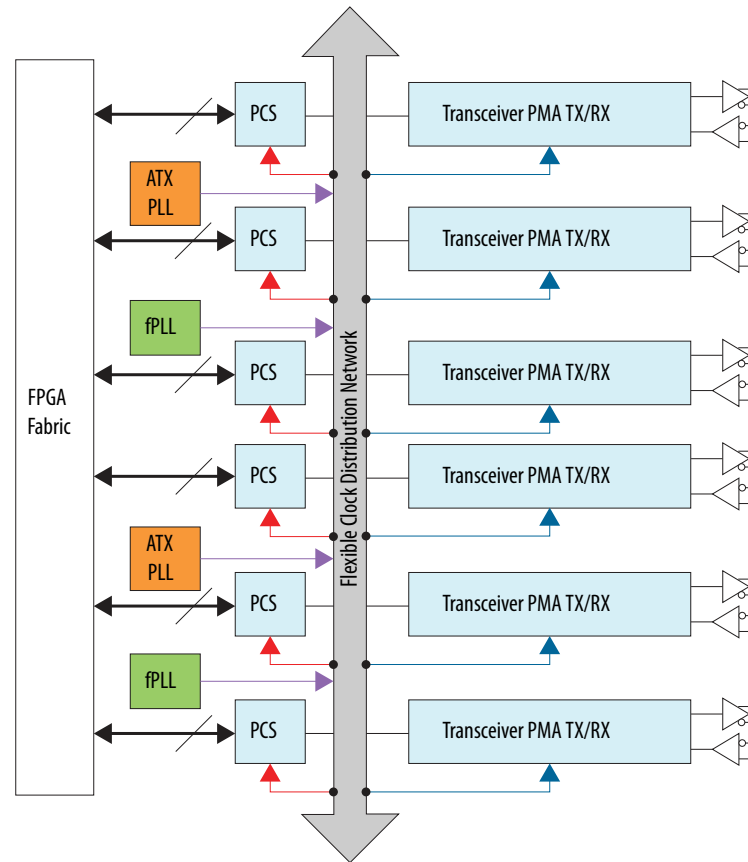
Intel Arria 10 transceivers support various data rates according to application:

- Chip-to-chip and chip-to-module applications—from 1 Gbps up to 25.8 Gbps
- Long reach and backplane applications—from 1 Gbps up to 12.5 with advanced adaptive equalization
- Critical power sensitive applications—from 1 Gbps up to 11.3 Gbps using lower power modes

The combination of 20 nm process technology and architectural advances provide the following benefits:

- Significant reduction in die area and power consumption
- Increase of up to two times in transceiver I/O density compared to previous generation devices while maintaining optimal signal integrity
- Up to 72 total transceiver channels—you can configure up to 6 of these channels to run as fast as 25.8 Gbps
- All channels feature continuous data rate support up to the maximum rated speed

**Figure 6. Intel Arria 10 Transceiver Block Architecture**



## Transceiver Channels

All transceiver channels feature a dedicated Physical Medium Attachment (PMA) and a hardened Physical Coding Sublayer (PCS).

- The PMA provides primary interfacing capabilities to physical channels.
- The PCS typically handles encoding/decoding, word alignment, and other pre-processing functions before transferring data to the FPGA core fabric.

A transceiver channel consists of a PMA and a PCS block. Most transceiver banks have 6 channels. There are some transceiver banks that contain only 3 channels.

A wide variety of bonded and non-bonded data rate configurations is possible using a highly configurable clock distribution network. Up to 80 independent transceiver data rates can be configured.

The following figures are graphical representations of top views of the silicon die, which correspond to reverse views for flip chip packages. Different Intel Arria 10 devices may have different floorplans than the ones shown in the figures.

## System Peripherals and Debug Access Port

Each Ethernet MAC, USB OTG, NAND flash controller, and SD/MMC controller module has an integrated DMA controller. For modules without an integrated DMA controller, an additional DMA controller module provides up to eight channels of high-bandwidth data transfers. Peripherals that communicate off-chip are multiplexed with other peripherals at the HPS pin level. This allows you to choose which peripherals interface with other devices on your PCB.

The debug access port provides interfaces to industry standard JTAG debug probes and supports ARM CoreSight debug and core traces to facilitate software development.

## HPS-FPGA AXI Bridges

The HPS-FPGA bridges, which support the Advanced Microcontroller Bus Architecture (AMBA) Advanced eXtensible Interface (AXI™) specifications, consist of the following bridges:

- FPGA-to-HPS AMBA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the FPGA fabric to issue transactions to slaves in the HPS.
- HPS-to-FPGA Avalon/AMBA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the HPS to issue transactions to slaves in the FPGA fabric.
- Lightweight HPS-to-FPGA AXI bridge—a lower latency 32 bit width bus that allows the HPS to issue transactions to soft peripherals in the FPGA fabric. This bridge is primarily used for control and status register (CSR) accesses to peripherals in the FPGA fabric.

The HPS-FPGA AXI bridges allow masters in the FPGA fabric to communicate with slaves in the HPS logic, and vice versa. For example, the HPS-to-FPGA AXI bridge allows you to share memories instantiated in the FPGA fabric with one or both microprocessors in the HPS, while the FPGA-to-HPS AXI bridge allows logic in the FPGA fabric to access the memory and peripherals in the HPS.

Each HPS-FPGA bridge also provides asynchronous clock crossing for data transferred between the FPGA fabric and the HPS.

## HPS SDRAM Controller Subsystem

The HPS SDRAM controller subsystem contains a multiport SDRAM controller and DDR PHY that are shared between the FPGA fabric (through the FPGA-to-HPS SDRAM interface), the level 2 (L2) cache, and the level 3 (L3) system interconnect. The FPGA-to-HPS SDRAM interface supports AMBA AXI and Avalon® Memory-Mapped (Avalon-MM) interface standards, and provides up to six individual ports for access by masters implemented in the FPGA fabric.

The HPS SDRAM controller supports up to 3 masters (command ports), 3x 64-bit read data ports and 3x 64-bit write data ports.

To maximize memory performance, the SDRAM controller subsystem supports command and data reordering, deficit round-robin arbitration with aging, and high-priority bypass features.



## FPGA Configuration and HPS Booting

The FPGA fabric and HPS in the SoC FPGA must be powered at the same time. You can reduce the clock frequencies or gate the clocks to reduce dynamic power.

Once powered, the FPGA fabric and HPS can be configured independently thus providing you with more design flexibility:

- You can boot the HPS independently. After the HPS is running, the HPS can fully or partially reconfigure the FPGA fabric at any time under software control. The HPS can also configure other FPGAs on the board through the FPGA configuration controller.
- Configure the FPGA fabric first, and then boot the HPS from memory accessible to the FPGA fabric.

## Hardware and Software Development

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Platform Designer system integration tool in the Intel Quartus Prime software.

For software development, the ARM-based SoC FPGA devices inherit the rich software development ecosystem available for the ARM Cortex-A9 MPCore processor. The software development process for Intel SoC FPGAs follows the same steps as those for other SoC devices from other manufacturers. Support for Linux\*, VxWorks\*, and other operating systems are available for the SoC FPGAs. For more information on the operating systems support availability, contact the Intel FPGA sales team.

You can begin device-specific firmware and software development on the Intel SoC FPGA Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.

## Dynamic and Partial Reconfiguration

The Intel Arria 10 devices support dynamic and partial reconfiguration. You can use dynamic and partial reconfiguration simultaneously to enable seamless reconfiguration of both the device core and transceivers.

### Dynamic Reconfiguration

You can reconfigure the PMA and PCS blocks while the device continues to operate. This feature allows you to change the data rates, protocol, and analog settings of a channel in a transceiver bank without affecting on-going data transfer in other transceiver banks. This feature is ideal for applications that require dynamic multiprotocol or multirate support.

### Partial Reconfiguration

Using partial reconfiguration, you can reconfigure some parts of the device while keeping the device in operation.



Date	Version	Changes
December 2015	2015.12.14	<ul style="list-style-type: none"> <li>Updated the number of M20K memory blocks for Arria 10 GX 660 from 2133 to 2131 and corrected the total RAM bit from 48,448 Kb to 48,408 Kb.</li> <li>Corrected the number of DSP blocks for Arria 10 GX 660 from 1688 to 1687 in the table listing floating-point arithmetic resources.</li> </ul>
November 2015	2015.11.02	<ul style="list-style-type: none"> <li>Updated the maximum resources for Arria 10 GX 220, GX 320, GX 480, GX 660, SX 220, SX 320, SX 480, and SX 660.</li> <li>Updated resource count for Arria 10 GX 320, GX 480, GX 660, SX 320, SX 480, a SX 660 devices in <b>Number of Multipliers in Intel Arria 10 Devices</b> table.</li> <li>Updated the available options for Arria 10 GX, GT, and SX.</li> <li>Changed instances of <i>Quartus II</i> to <i>Quartus Prime</i>.</li> </ul>
June 2015	2015.06.15	Corrected label for Intel Arria 10 GT product lines in the vertical migration figure.
May 2015	2015.05.15	Corrected the DDR3 half rate and quarter rate maximum frequencies in the table that lists the memory standards supported by the Intel Arria 10 hard memory controller.
May 2015	2015.05.04	<ul style="list-style-type: none"> <li>Added support for 13.5G JESD204b in the Summary of Features table.</li> <li>Added a link to Arria 10 GT Channel Usage in the Arria 10 GT Package Plan topic.</li> <li>Added a note to the table, Maximum Resource Counts for Arria 10 GT devices.</li> <li>Updated the power requirements of the transceivers in the Low Power Serial Transceivers topic.</li> </ul>
January 2015	2015.01.23	<ul style="list-style-type: none"> <li>Added floating point arithmetic features in the Summary of Features table.</li> <li>Updated the total embedded memory from 38.38 megabits (Mb) to 65.6 Mb.</li> <li>Updated the table that lists the memory standards supported by Intel Arria 10 devices.</li> <li>Removed support for DDR3U, LPDDR3 SDRAM, RLDRAM 2, and DDR2.</li> <li>Moved RLDRAM 3 support from hard memory controller to soft memory controller. RLDRAM 3 support uses hard PHY with soft memory controller.</li> <li>Added soft memory controller support for QDR IV.</li> <li>Updated the maximum resource count table to include the number of hard memory controllers available in each device variant.</li> <li>Updated the transceiver PCS data rate from 12.5 Gbps to 12 Gbps.</li> <li>Updated the max clock rate of PS, FPP x8, FPP x16, and Configuration via HPS from 125 MHz to 100 MHz.</li> <li>Added a feature for fractional synthesis PLLs: PLL cascading.</li> <li>Updated the HPS programmable general-purpose I/Os from 54 to 62.</li> </ul>
September 2014	2014.09.30	<ul style="list-style-type: none"> <li>Corrected the 3 V I/O and LVDS I/O counts for F35 and F36 packages of Arria 10 GX.</li> <li>Corrected the 3 V I/O, LVDS I/O, and transceiver counts for the NF40 package of the Arria GX 570 and 660.</li> <li>Removed 3 V I/O, LVDS I/O, and transceiver counts for the NF40 package of the Arria GX 900 and 1150. The NF40 package is not available for Arria 10 GX 900 and 1150.</li> </ul>
continued...		